

#	Layer	Thickness	Description	Note
	Top Solder	0.015mm	Soldermask IPC-SM840	used on rigid parts
	Top Surface Finish	0.006mm		
1	Top Side	0.035mm	Starting foil 1/2oz. after plating and processing	
		0.220mm	Prepreg IPC-4101/21	FR-4.0
2	Inner Layer 1	0.017mm	ED Base Copper	
		0.360mm	Core IPC-4101/21	FR-4.0
3	Inner Layer 2	0.017mm	ED Base Copper	
		0.220mm	Prepreg IPC-4101/21	FR-4.0
4	Inner Layer 3	0.017mm	ED Base Copper	
		0.360mm	Core IPC-4101/21	FR-4.0
5	Inner Layer 4	0.017mm	ED Base Copper	
		0.220mm	Prepreg IPC-4101/21	FR-4.0
6	Bottom Side	0.035mm	Starting foil 1/2oz. after plating and processing	
	Bottom Surface Finish	0.006mm		
	Bottom Solder	0.015mm	Soldermask IPC-SM840	used on rigid parts

Total thickness: 1.559mm

notes:

Final copper thicknesses according to IPC-6012

Standard: Surface Finish ENIG
(Ni 5.5 µm ± 1.5 µm, Au 0.075 µm ± 0.025 µm)

Please follow our sectional design rules:
► www.we-online.com/designrulesbasic_en

For impedance matching stackups: Please consult our specialists: BASIC@we-online.com

BASIC6_ML6_155_17_2V13

PCB Thickness Tolerance: ± 10%

customer		created	
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pcb name		approved	
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engineer		format	A4, landscape
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date			
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Template Revision: 10/2023 by Andreas Schilpp / Michael Kress / Werner Öchslen



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